

## MICROPROCESSOR BASED SELF-DIAGNOSTIC PORT

## BACKGROUND OF THE INVENTION

## 1. Field of the Invention

The invention relates to testing integrated circuits. More particularly, the invention relates to an on-chip implementation of a JTAG (Joint Test Action Group) master which can effect a plurality of predefined tests of the chip without regard to other devices on the same circuit board.

## 2. State of the Art

Over the years printed circuit boards (PCBs) have grown in complexity. Advances in surface mount packaging and PCB manufacturing have resulted in smaller PCBs with chips spaced closer to each other than in the past. Thus, modern PCBs can not always be tested with traditional tools, e.g. physical test probes applied to the board externally.

In the 1980s, the Joint Test Action Group (JTAG) developed a specification for boundary scan testing (BST) that was later standardized as IEEE 1149.1. The BST can test pin connections without the use of physical test probes. The BST standard defines a serial protocol for accessing and controlling the signal-levels on the pins of a digital circuit, and has some extensions for

1 testing the internal circuitry on the chip itself. All the  
2 signals between the chip's core logic and its pins are intercepted  
3 by a serial scan path known as the "Boundary Scan Register" (BSR).  
4 In normal system operation this path can transparently connect the  
5 core-logic signals to the pins and effectively become invisible.  
6 In external-test mode, it can disconnect the core-logic from the  
7 pins, drive the output pins by itself, and read and latch the  
8 states of the input pins. In internal-test mode, it can  
9 disconnect the core-logic from the pins, drive the core-logic  
10 input signals by itself, and read and latch the states of the  
11 core-logic output signals. The interface to the BST is via five  
12 pins and an on-chip TAP (test access port) controller state  
13 machine.

14

15 The JTAG interface uses the following five dedicated signals  
16 which must be provided on each chip that supports the standard:

17 TRST, a Test-ReSeT input which initializes and disables the  
18 test interface;

19 TCK, the Test CLoCK input which controls the timing of the  
20 test interface independently from any system clocks. TCK is pulsed  
21 by the equipment controlling the test and not by the tested  
22 device. It can be pulsed at any frequency (up to a maximum of  
23 some MHz). It can be even pulsed at varying rates;

24 TMS, the Test Mode Select input which controls the  
25 transitions of the test interface state machine;

1       TDI, the Test Data Input line, which supplies the data to the  
2 JTAG registers (Boundary Scan Register, Instruction Register, or  
3 other data registers); and

4       TDO, the Test Data Output line, which is used to serially  
5 output the data from the JTAG registers to the equipment  
6 controlling the test. It carries the sampled values from the  
7 boundary scan chain (or other JTAG registers) and propagates them  
8 to the next chip in the serial test circuit.

9  
10       The normal organization of the test circuit on a board that  
11 incorporates several chips with JTAG support is to connect TRST,  
12 TCK, and TMS to every chip in parallel, and to connect TDO from  
13 one chip to TDI of the next in a single loop. This presents a  
14 single JTAG test interface for the board. It is possible to  
15 provide individual access to each chip on the board but it would  
16 require the use of five board pins for each chip.

17  
18       Although the JTAG interface has proved to be very effective,  
19 it is limited in some ways. First, in order to test a single chip  
20 on a PCB it may be necessary to remove the chip from the board.  
21 Although it is possible to test individual chips on a board  
22 without removing them from the board, it is necessary to take the  
23 board out of service to perform the tests. Further, in order to  
24 implement JTAG tests, the board developer must be aware of various  
25 parameters for each of the chips on the board.

1        On the chip level, JTAG has been used by manufacturers to  
2 test a chip for compliance with the manufacturer's specifications.  
3 It would be useful for board developers to be able to perform the  
4 same tests that the chip manufacturer uses to determine whether  
5 the chip is operating properly. It would also be desirable for  
6 the chip manufacturer to provide the board developer with a turn-  
7 key testing solution. These objects, however, are not easily  
8 achievable. In order to provide a turn-key solution for a chip  
9 which is being used on the developer's board, the chip  
10 manufacturer would need to know the particulars about the board  
11 and how the JTAG interface(s) are implemented on the board. This  
12 is impractical because chip manufacturers want to make their chips  
13 as versatile as possible so that they may be used on many  
14 different board applications.

#### 16                                SUMMARY OF THE INVENTION

18        It is therefore an object of the invention to provide methods  
19 and apparatus for enabling diagnostic testing of a chip on a  
20 circuit board.

22        It is also an object of the invention to provide methods and  
23 apparatus for enabling diagnostic testing of a chip on a circuit  
24 board which do not require removing the chip from the board or  
25 taking the board out of service.

1       It is another object of the invention to provide methods and  
2 apparatus for enabling diagnostic testing of a chip on a circuit  
3 board which enable the chip manufacturer to provide a single  
4 testing solution for the chip which will work properly regardless  
5 of the board on which the chip is used.

6  
7       It is still another object of the invention to provide  
8 methods and apparatus for selecting between standard JTAG testing  
9 and testing according to the invention.

10  
11       In accord with these objects which will be discussed in  
12 detail below, the present invention provides an application  
13 specific integrated circuit (ASIC) having a JTAG interface and a  
14 microprocessor interface. According to the invention, the ASIC is  
15 also provided with an on-chip JTAG master which is coupled to the  
16 JTAG interface and the microprocessor interface. The  
17 microprocessor interface is provided with a plurality of registers  
18 which are mapped to the five JTAG signals and additional registers  
19 which are used to conduct a plurality of tests. The methods of  
20 the invention include controlling the on-chip JTAG master via an  
21 off-chip microprocessor coupled to the microprocessor interface.

22  
23       Using the invention, diagnostic tests of the chip can be  
24 performed without removing the chip from the board and without  
25 removing the board from service. Board developers and device

1 maintenance personnel can perform the same diagnostic tests as the  
2 manufacturer to determine whether the chip is performing according  
3 to specification. The invention therefore allows more accurate  
4 tests of in-service boards which are part of a larger device, e.g.  
5 a telecommunications switch. In addition, since the board does  
6 not need to be taken out of service, the invention can be  
7 advantageously used to create single chip systems. With the  
8 invention, a chip manufacturer can supply developers with a set of  
9 diagnostic programs which can be used to test the chip regardless  
10 of how the board carrying the chip is designed. The present  
11 implementation of the invention allows the same JTAG master and  
12 microprocessor interface to be used on many different chips  
13 without modification.

14  
15 Additional objects and advantages of the invention will  
16 become apparent to those skilled in the art upon reference to the  
17 detailed description taken in conjunction with the provided  
18 figures.

19  
20 BRIEF DESCRIPTION OF THE DRAWINGS

21  
22 Figure 1 is a high level block diagram of an ASIC according  
23 to the invention; and  
24

1        Figure 2 is a high level block diagram of a synchronization  
2 circuit which is used to switch between the microprocessor control  
3 of the JTAG TAP and traditional control of the JTAG TAP.

4  
5                DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS  
6

7        Referring now to Figure 1, an ASIC 10 according to the  
8 invention includes core logic 12 which provides the primary  
9 functions of the ASIC and which is coupled to a plurality of pins  
10 (not shown). In addition, the ASIC 10 is provided with a standard  
11 JTAG TAP 14 which is coupled to the core logic 12 and selectively  
12 coupled to the standard JTAG five pin interface TRST, TMS, TCK,  
13 TDI, and TDO. According to the invention an on-chip JTAG Master  
14 16 is selectively coupled to the JTAG TAP 14. The JTAG master 16  
15 is coupled to an 8-bit microprocessor interface 20 via a plurality  
16 of status and control registers 18.

17  
18        More particularly the TDO output of the JTAG TAP is coupled  
19 to a TDO input of the JTAG Master and via a switch 22 to the  
20 standard TDO pin on the chip 10. The switch 22 is operated by  
21 output from an OR gate 24 which receives input from both the JTAG  
22 TAP (TDO output enable) and a select signal from the JTAG Master.  
23 The JTAG master 16 outputs TRST, TMS, TCK, and TDI signals to a  
24 switch 26 which is also coupled the TRST, TMS, TCK, and TDI pins.  
25 The select signal from the JTAG Master 16 activates both switches

22 and 26 to override the JTAG pins on the chip and substitute the JTAG Master for them. The JTAG Master also receives a select reset signal from the TRST pin. As shown in the Figures, the TRST, TMS, TCK, and TDI pins are each associated with an input buffer 28, 30, 32, 34.

The status and control registers 18 include the following registers identified in Table 1.

Register Name	MP Access	Function
TCK_Divider	R/W	A clock divider number (divisor) used to create a 10MHz TCK from the system clock
Counter	R/W	6-Bit shift count register.
TDI_FIFO_B0	R/W	Byte 0 of a (5x8 deep) FIFO containing TDI data to send to the TAP
TDI_FIFO_B1	R/W	Byte 1 of a (5x8 deep) FIFO containing TDI data to send to the TAP
TDI_FIFO_B2	R/W	Byte 2 of a (5x8 deep) FIFO containing TDI data to send to the TAP
TDI_FIFO_B3	R/W	Byte 3 of a (5x8 deep) FIFO containing TDI data to send to the TAP
TDI_FIFO_B4	R/W	Byte 4 of a (5x8 deep) FIFO containing TDI data to send to the TAP
TMS_FIFO_B0	R/W	Byte 0 of a (5x8 deep) FIFO containing TMS data to send to the TAP
TMS_FIFO_B1	R/W	Byte 1 of a (5x8 deep) FIFO containing TMS data to send to the TAP
TMS_FIFO_B2	R/W	Byte 2 of a (5x8 deep) FIFO containing TMS data to send to the TAP
TMS_FIFO_B3	R/W	Byte 3 of a (5x8 deep) FIFO containing TMS data to send to the TAP



TMS_FIFO_B4	R/W	Byte 4 of a (5x8 deep) FIFO containing TMS data to send to the TAP
TDO_FIFO_B0	R	Byte 0 of a (5x8 deep) FIFO containing TDO data received from the TAP
TDO_FIFO_B1	R	Byte 1 of a (5x8 deep) FIFO containing TDO data received from the TAP
TDO_FIFO_B2	R	Byte 2 of a (5x8 deep) FIFO containing TDO data received from the TAP
TDO_FIFO_B3	R	Byte 3 of a (5x8 deep) FIFO containing TDO data received from the TAP
TDO_FIFO_B4	R	Byte 4 of a (5x8 deep) FIFO containing TDO data received from the TAP
Start	R/W	Start bit is set to trigger a transfer between the microprocessor and the TAP via the JTAG Master. This bit clears the End bit.
End	R	When a transfer is completed, this bit is set.
JM_TRSTN	R/W	The value of TRST driven by the microprocessor interface. Initializes to logical '0'.
TDI_Loop_Back	R/W	This bit loops back the TDI FIFO output, back into the TDO FIFO input. Used to test the interface.
TMS_Loop_Back	R/W	This bit loops back the TMS FIFO output, back into the TDO FIFO Input. Used to test the interface
TRSTN_Sample	R	This bit samples what the microprocessor interface is driving into the TAP
MP_CNTRL	R/W	This bit switches TAP control from pins to the on-chip JTAG master

Table 1

According to the presently preferred embodiments, the ASICs according to the invention are designed for use in telecommunications switching. These chips are generally provided

1 with a microprocessor interface which is connected to a host for  
2 configuring the telecommunications switch, e.g. provisioning  
3 circuits, establishing quality of services parameters, managing  
4 queues, etc. The present invention makes use of this existing  
5 microprocessor interface to control the new on-chip JTAG master  
6 via the registers described above which coordinate the handshake  
7 between the host processor and the JTAG master, and issue  
8 instructions and operations to the target on-chip TAP state  
9 machine.

10  
11 Some of the features which are available via the  
12 microprocessor interface include memory built-in self-test (BIST),  
13 logic BIST, manufacturing ID codes, memory BIST diagnostic data,  
14 special configuration registers, RAM repair information, etc.

15  
16 Two FIFOs are used to control the TAP, the TDI FIFO and the  
17 TMS FIFO. The TDI (test data input) FIFO is filled with the data  
18 to be used in the test and the TMS (test mode select) FIFO is  
19 filled with control information associated with each TDI bit that  
20 will be applied to the TAP. The six-bit Counter is initialized  
21 with the six-bit binary representation of the number of bits to be  
22 shifted. As the TMS and TDI FIFOs are each 5x8, the maximum  
23 number of bits to be shifted is forty. Once these three registers  
24 are initialized, the Start bit is set and the JTAG master state  
25 machine reads each bit from the TDI & TMS FIFOs, and places them

1 sequentially on the TDI and TMS inputs of the TAP. At the same  
2 time, the JTAG master shifts TDO bits into the TDO FIFOs where  
3 they can be read by the microprocessor. When the counter expires,  
4 the End bit is set, and the last bit of the TMS register is held  
5 on the TAP inputs.

6  
7 According to the invention, the FIFOs are kept small to  
8 conserve space on the chip. In the presently preferred embodiment  
9 the FIFOs are no larger than 40 bits. However, by exploiting  
10 features of the TAP standard, operations larger than 40 bits can  
11 be achieved.

12  
13 The TAP state machine is designed to allow four states to be  
14 held in place without shifting in new data. These states, which  
15 are held in place based on the TMS value, are as follows:

16 State 1: Test-Logic-Reset -- This clears all the internal  
17 states of the TAP. Not used during test.

18 State 2: Run-Test-Idle -- This state is the 'No-Op'  
19 equivalent for the TAP. No operation occurs, but active tests can  
20 still be running inside the ASIC. This state will not interfere  
21 with them, even though, the tests were initiated by the TAP.

22 State 3: Pause-IR -- This state is a pause in the shift of  
23 the IR. From this state, the user has the option to go back to  
24 shift the IR some more bits, or exit and update the IR.

1       State 4: Pause-DR -- This state is similar to the Pause-IR,  
 2   but used for the internal Data Register. So, by loading the TMS &  
 3   TDI fifos with a sequence of bits, the TAP can be cycled through  
 4   its state elements, and held into one of the above states,  
 5   depending on what needs to be done.

6  
 7       The following sequence, when loaded into the TMS & TDI FIFOs,  
 8   will take the TAP out of Test-Logic-Reset state and place it in  
 9   the Run-Test-Idle: state. It will also, hold the TMS to a value  
 10   of '1', which will keep the TAP in the Run-Test-Idle state.

11  
 12               TMS\_Fifo: 00  
 13               TDI\_Fifo: XX  
 14               Count: 2  
 15

16       The following sequence will load a sequence of 40-bits into  
 17   the DR register and read the 40 DR status bits into the TDO FIFO.  
 18   When the first operation is completed, the TAP will be held in the  
 19   Pause-DR state when TMS is '0', then next operation set will  
 20   complete the shift, and put the TAP back into the Run-Test-Idle  
 21   state (assuming it starts in the Run-Test-Idle state):

22  
 23   TMS\_Fifo: 1000 0000 0000 0000 0000 0000 0000 0000 0000 0010  
 24   TDI\_Fifo: XXX0 1234 5678 9012 3456 7890 1234 5678 9012 345X  
 25   Count: 40  
 26

27   The resulting state sequence is from Run-Test-idle to Select-DR-  
 28   Scan to Capture-DR to Shift-DR (36 times) to Exit1-DR to Pause-DR

1 (N times). This will pause the shifting of the DR for as long as  
2 it takes the microprocessor to read the DR status bits from the  
3 TDO FIFO and to initialize the next new transaction.

4  
5 The following sequence will shift from Pause-DR to Exit2-DR  
6 to Shift-DR (6 times) to Exit1-DR to Update-DR to Run-Test-Logic  
7 (N times).

8  
9 TMS\_Fifo: 1000 0001 1000  
10 TDI\_Fifo: XX45 6789 XXXX  
11 Count: 12  
12

13 These operation sets are a subset of the full capability of the  
14 TAP, but are sufficient to load/unload all the internal TAP states  
15 including the IR and device ID registers.

16  
17 The switching mechanism, shown generally in Figure 1 at 22,  
18 24, 26, is designed to default to the normal JTAG interface. When  
19 the microprocessor is to take control of the TAP, a signal  
20 internal to the system is used to generate the switch. This  
21 signal is identified as "Select" in the JTAG master 16.  
22 Implementation of this signal may cause a problem if the system  
23 has not been initialized, and a bad value might be issued that  
24 makes the TAP inaccessible to the outside controls. Figure 2  
25 shows the synchronization circuit that insures the proper

1 operation of both the normal JTAG TAP & the microprocessor interface.

2  
3 As shown in Figure 2, the select signal from the JTAG master  
4 16, which is controlled by the contents of MP CNTRL REGISTER 18',  
5 is NORed with a board level test pin. In Figure 2 this pin is  
6 labeled "HIGH Z", but any other board level test pin could be  
7 used. This pin is normally asserted (driven to 0) when the chip  
8 is operational. The circuit behaves in the following manner:

9 For tests run on the tester, the tests will strictly rely on  
10 the TAP being driven from the primary I/O pins. By asserting the  
11 HIGH Z pin to 1, the output of the NOR gate will always be 0,  
12 causing the standard JTAG interface to control the TAP. This  
13 requires that the HIGH Z pin be considered an IEEE 1149 compliance  
14 pin during any JTAG activity, while the ASIC is in stand alone  
15 mode.

16  
17 For tests run in a system, tests will require that the HIGH Z  
18 pin be driven to 0, and the MP CNTRL REGISTER will select the  
19 source controlling the TAP. The MP CNTRL REGISTER is initialized  
20 to 1 with the microprocessor interface at the time the  
21 microprocessor interface is initialized. As such, the in-system  
22 TAP will default on power up to control by the external pins, and  
23 can be selected by the microprocessor to be controlled by on board  
24 signals from the JTAG master.

1       A prototype of the invention was synthesized for 0.18 $\mu$ m and  
2   0.13 $\mu$ m TSMC Artisan Libraries. The resulting area of this block  
3   is approximately 5000 gates which represents a very minimal area  
4   overhead in the state of the art.

5  
6       Referring once again to Table 1, the microprocessor interface  
7   can also be tested for correctness of operation. The interface  
8   can be placed into loop-back where either the TMS FIFO or the TDI  
9   FIFO is fed into the TDO FIFO. This loop back scheme allows the  
10   microprocessor interface to fully test bus accesses and the FIFOs  
11   used to drive the TAP. TRST can be sampled through the  
12   TRST\_sample register, and its value confirmed.

13  
14       There have been described and illustrated herein an  
15   integrated circuit with an on-chip JTAG master coupled to a  
16   microprocessor interface. While particular embodiments of the  
17   invention have been described, it is not intended that the  
18   invention be limited thereto, as it is intended that the invention  
19   be as broad in scope as the art will allow and that the  
20   specification be read likewise. It will therefore be appreciated  
21   by those skilled in the art that yet other modifications could be  
22   made to the provided invention without deviating from its spirit  
23   and scope as so claimed.